MULTILAYER CERAMIC ANTENNA (LINEAR POLARIZATION MODE) FOR 433MHz

Preliminary Product Specification

QUICK REFERENCE DATA

Working Frequency 433 MHz

Bandwidth 20 MHz (Min)

Frequency Range $421 \sim 445 \text{ MHz}$

Gain 0.5 dBi (Max)

VSWR 2.0 max

Polarization Linear

Azimuth Omni-directional

Impedance 50Ω

Operating Temperature -55~125 °C

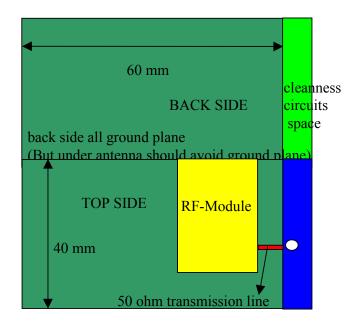
Termination Ni/Sn (Environmentally-Friendly Leadless)

Resistance to soldering heat 260°C, 10 sec.

Special Environmental Concerns- Green Products Design: The foil making process is using environmentally friendly aqueous solvent technology. Termination is lead free and packing materials can be re-cycled

1. APPLICATION

R&D	Print date 02/03/21	Print date 02/03/21 Preliminary					use only	
						20	01-10-06	
	Multilayer Ceramic Antenna			4313 121 20043			2001-11-01	
	for 433MHz	for 433MHz			<u> </u>			
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2. SOLDER LAND PATTERN FOR ANTENNA

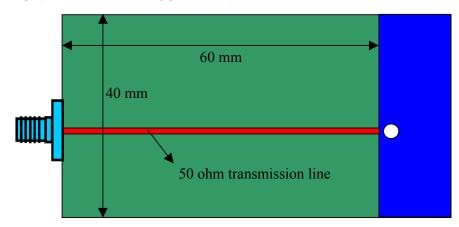
Figure		Dimensions	Remark
	L	$8.0 \pm 0.50 \text{ mm}$	
$C \longrightarrow S \longrightarrow$	F	$3.50 \pm 0.50 \text{ mm}$	Feed pad
	С	$0.90 \pm 0.10 \text{ mm}$	
L	S	$3.50 \pm 0.50 \text{ mm}$	Mount pad
C •			
F			

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3. MECHANICAL DATA

Figure	I	Dimension	Port
w W	L	7.2±0.5mm	-
C	W	38.0±0.5mm	-
	T	0.90±0.1mm	-
<u></u> C	F	3.0±0.8mm	Feed termination
\bullet D \bullet S \bullet D	C	0.5±0.3mm	-
↑ <u> </u>	D	17.5±0.3mm	Solder termination
	S	2.0±0.8mm	-
→ _F ←			

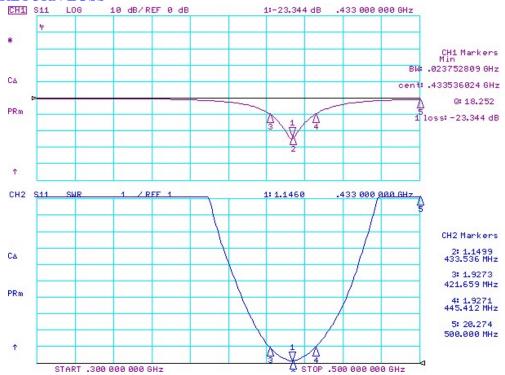
4. TEST BOARD DIMENSION FOR S11 (RETURN LOSS) AND RADIATION PATTERN MEASURNMENT



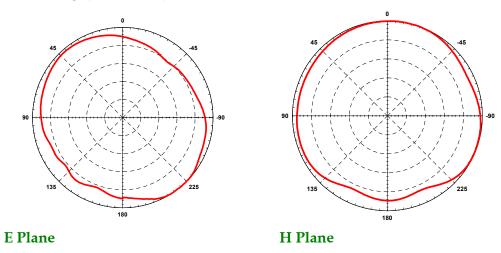
FR-4 PCB thickness = 0.8 mmThe length of transmission line = 1.35 mm (depends on PCB thickness)

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5. S11 RETURN LOSS



6. RADIATION PATTERN



Antenna Gain = 2.2 dBi

RELIABILITY DATA (Reference to IEC Specification)

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IEC 384-10/ CECC 32 100 CLAUSE	IEC 6006868-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
4.4		Mounting	The antenna can be mounted on printed-circuit boards or ceramic substrates by applying wave soldering, reflow soldering (including vapour phase soldering) or conductive adhesive	No visible damage
4.5		Visual inspection and dimension check	Any applicable method using × 10 magnification	In accordance with specification (no chip off 3 mm)
4.6.1		Antenna	Frequency = 433MHz at 20°C	Standard test board on page 4
4.8		Adhesion	A force of 5 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate	No visible damage
4.9		Bond strength of plating on end face	Mounted in accordance with CECC 32 100, paragraph 4.4	No visible damage
			Conditions: bending 0.5 mm at a rate of 1mm/s, radius jig. 340 mm, 1 mm warp on FR4 board of 90 mm length	No visible damage
4.10	Tb	Resistance to soldering heat	260 ± 5 °C for 10 ± 0.5 s in a static solder bath	The terminations shall be well tinned after recovery and Central Freq. Change ± 6%

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	Multilayer Ceramic for 433MHz	Antenna	4	1313 121	20043	20	001-11-01	
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IEC 384-10/ CECC 32 100 CLAUSE	IEC 6006868-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
		Resistance to leaching	260 ± 5 °C for 30 ± 1 s in a static solder bath	Using visual enlargement of × 10, dissolution of the termination shall not exceed 10%
4.11	Та	Solderability	Zero hour test, and test after storage (20 to 24 months) in original atmosphere; un-mounted chips completely immersed for 2 ± 0.5 s in 235 ± 5 °C.	The termination must be well tinned, at least 75% is well tinned at termination
4.12	Na	Rapid change of temperature	-55 °C (30 minutes) to +125 °C (30 minutes); 100 cycles	No visible damage Central Freq. Change ± 6%
4.14	Ca	Damp heat	500 ± 12 hours at 60 °C; 90 to 95 % RH	No visible damage 2 hours recovery Central Freq. Change ± 6%
4.15		Endurance	500 ± 12 hours at 125 °C	No visible damage 2 hours recovery Central Freq. Change ± 6%

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ORDERING INFORMATION: 12NC Ordering Code

The antennas may be ordered by using the 12 NC ordering code. These code numbers can be determined by the following rules:

43 = Antenna

F. Family Code

C. Packing Type Code

13 = Bulk, 1000 pcs

M. Materials Code

1 = High Frequency Material

S. Size Code

21 = 7.2 * 38.0 * 0.9mm

T. Tolerance

20 = 20 MHz Bandwidth

A. Working Frequency

043 = 433 MHz

Example: 12NC 4313 121 20043

Product description: Antenna (43) by bulk 1000 pcs (13) of High

Frequency Material (1), Size 7.2*38*0.9 mm (21);

Tolerance (20) of 20 MHz (VSWR<2)

Working Frequency (043) = 433MHz

ORDERING INFORMATION: Method II- by Clear Text Code (Temporary)

The antennas may be ordered by using the 16-digit clear text ordering code. These code numbers can be determined by the following rules:

	, U										
	AN0433200707381B (Clear Text Code Example)										
AN	0433	20	07	0738	1	В					
Product	Central Freq.	Bandwidth	Material	Size	Quantities	Packing					
AN=	0433=433MHz	20=>20MHz	07=K7	0738=7.2*38*	1 = 1K	B = Bulk					
Antenna				0.9 mm							

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